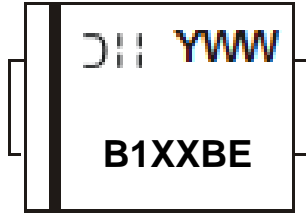


Marking Information (continued)

SMB



B1XXBE = Product Type Marking Code, ex: B150BE

= Manufacturers' Marking

YWW = Date Code Marking

Y = Last Digit of Year (ex: 0 for 2020)

WW = Week Code (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	B150AE B150BE	B160AE B160BE	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _{RM}	50	60	V
Average Rectified Output Current	I _O	1		A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	30		A

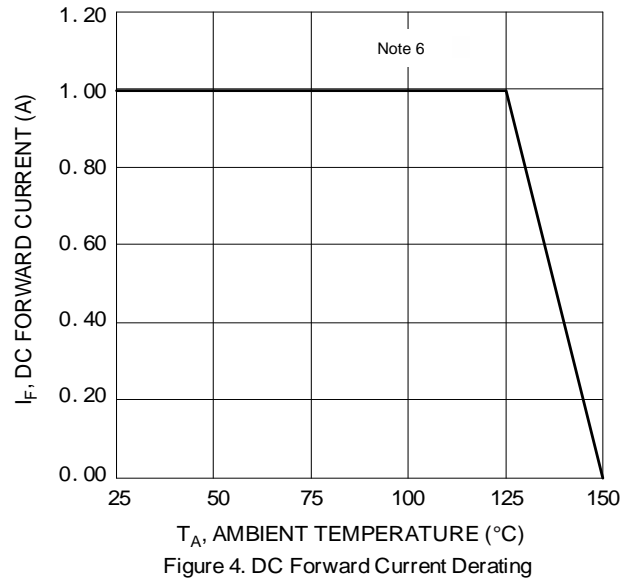
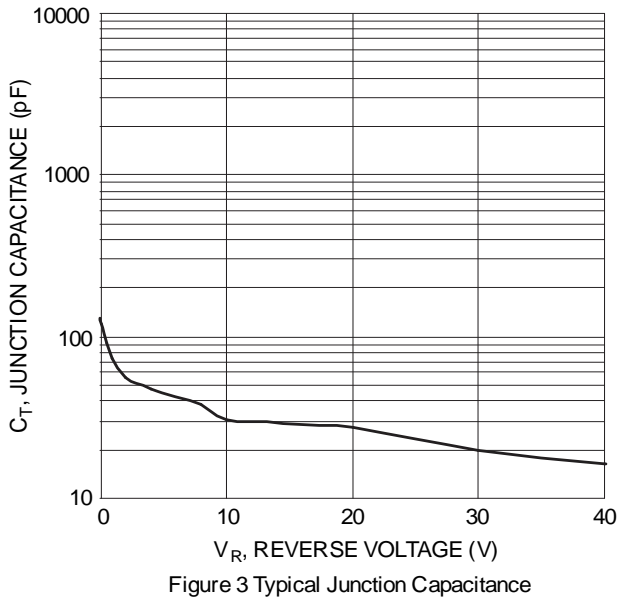
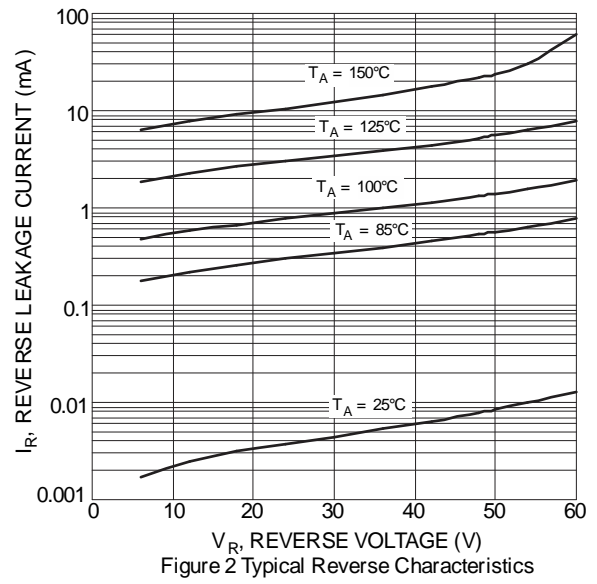
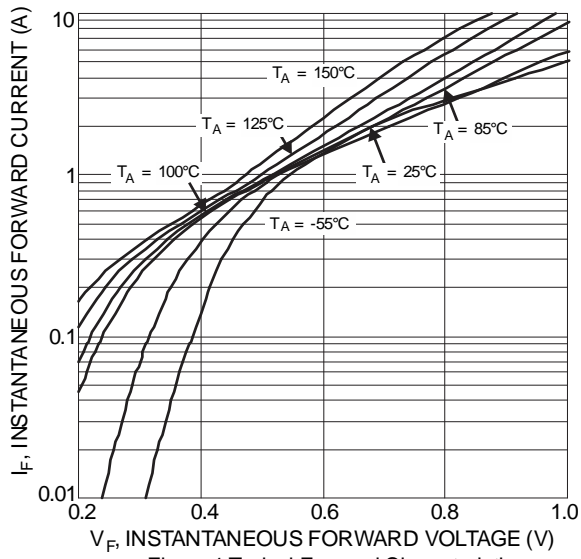
Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 6)	SMA SMB	95	°C/W
		90	
Typical Thermal Resistance Junction to Case (Note 6)	SMA SMB	45	°C/W
		40	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V _F	—	—	0.65	V	I _F = 1A, T _J = +25°C I _F = 1A, T _J = +125°C
Leakage Current (Note 7)	I _R	—	—	0.1	mA	V _R = 50V, T _J = +25°C
		—	—	0.2		V _R = 60V, T _J = +25°C
		—	8.0	—		V _R = 60V, T _J = +125°C
Typical Capacitance	C _T	—	45	—	pF	V _R = 4.0V, f = 1MHz

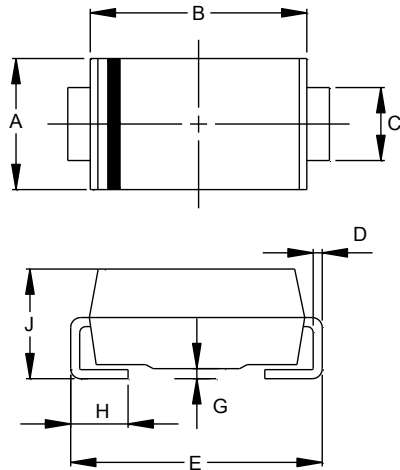
Notes: 6. Device mounted on FR-4 substrate, 0.4" × 0.5", 2oz, single-sided, PC boards with 0.2" × 0.25" copper pad.
7. Short duration pulse test used to minimize self-heating effect.



Package Outline Dimensions

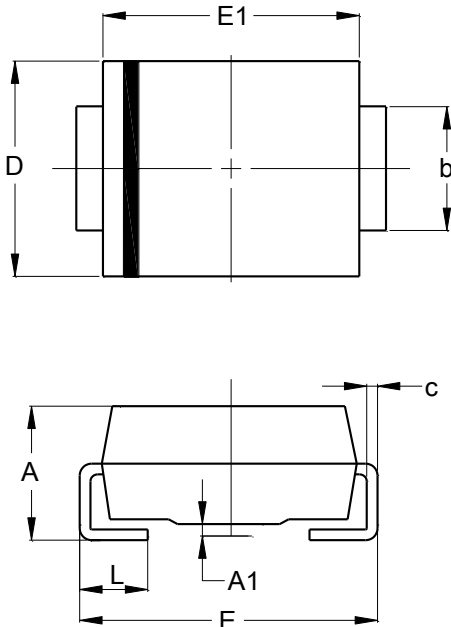
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(1) Package Type: SMA



SMA		
Dim	Min	Max
A	2.29	2.92
B	4.00	4.60
C	1.27	1.63
D	0.15	0.31
E	4.80	5.59
G	0.05	0.20
H	0.76	1.52
J	1.96	2.40
All Dimensions in mm		

(2) Package Type: SMB

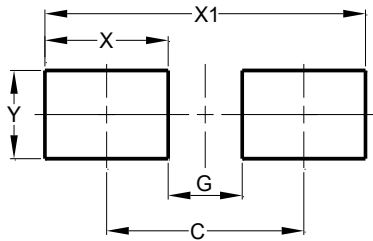


SMB		
Dim	Min	Max
A	2.00	2.50
A1	0.05	0.20
b	1.96	2.21
c	0.15	0.31
D	3.30	3.94
E	5.00	5.59
E1	4.06	4.57
L	0.76	1.52
All Dimensions in mm		

Suggested Pad Layout

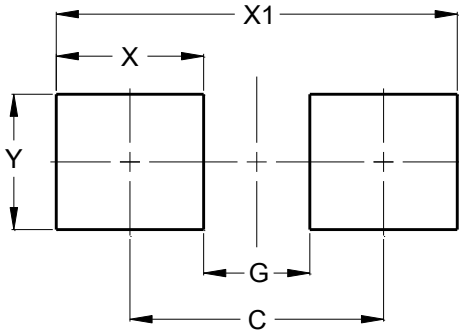
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(1) Package Type: SMA



Dimensions	Value (in mm)
C	4.00
G	1.50
X	2.50
X1	6.50
Y	1.70

(2) Package Type: SMB



Dimensions	Value (in mm)
C	4.30
G	1.80
X	2.50
X1	6.80
Y	2.30

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